



FAST CMOS 20-BIT TRANSPARENT LATCH

IDT74FCT16841AT/CT

FEATURES:

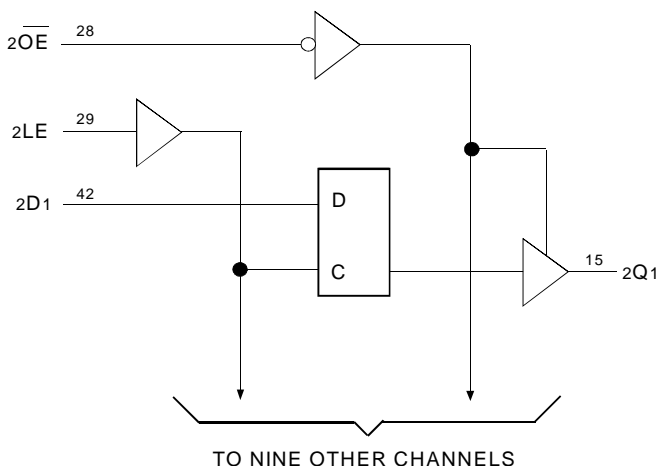
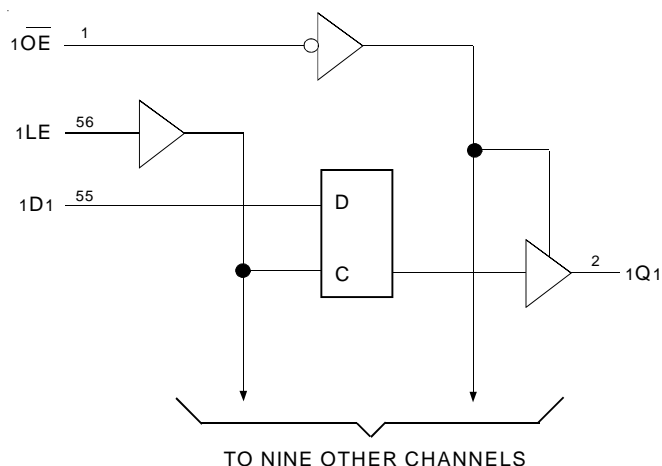
- 0.5 MICRON CMOS Technology
- High-speed, low-power CMOS replacement for ABT functions
- Typical $t_{sk(o)}$ (Output Skew) < 250ps
- Low input and output leakage $\leq 1\mu A$ (max.)
- $V_{CC} = 5V \pm 10\%$
- High drive outputs (-32mA I_{OH} , 64mA I_{OL})
- Power off disable outputs permit "live insertion"
- Typical V_{OLP} (Output Ground Bounce) < 1.0V at $V_{CC} = 5V$, $T_A = 25^\circ C$
- Available in SSOP and TSSOP packages

DESCRIPTION:

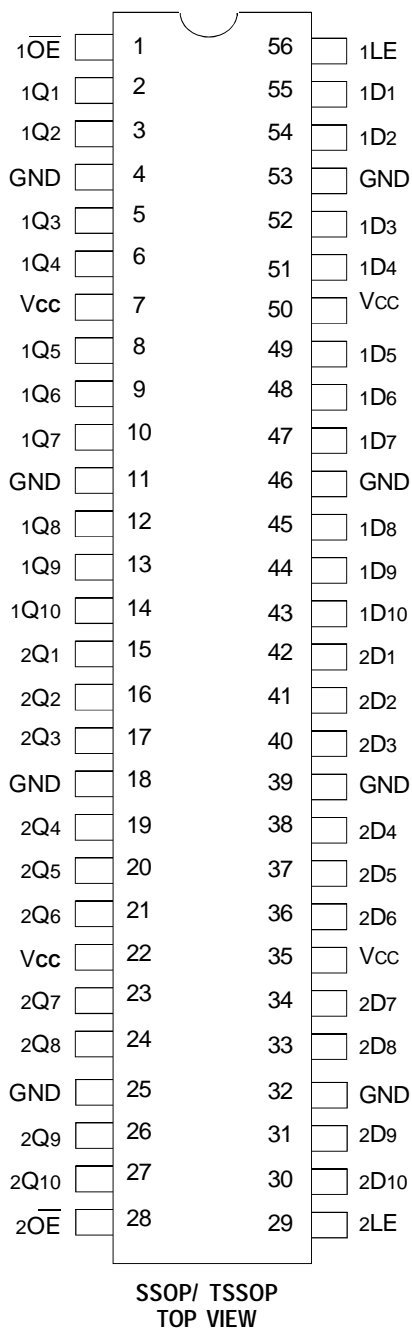
The FCT16841T 20-bit transparent D-type latch is built using advanced dual metal CMOS technology. These high-speed, low-power latches are ideal for temporary data storage. They can be used for implementing memory address latches, I/O ports, and bus drivers. The Output Enable (\overline{OE}) and Latch Enable (LE) controls are organized to operate each device as two 10-bit latches or one 20-bit latch. Flow-through organization of signal pins simplifies layout. All inputs are designed with hysteresis for improved noise margin.

The FCT16841T is ideally suited for driving high capacitance loads and low impedance backplanes. The output buffers are designed with power off disable capability to allow "live insertion" of boards when used as backplane drivers.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to V _{CC} +0.5	V
TSTG	Storage Temperature	-65 to +150	°C
I _{OUT}	DC Output Current	-60 to +120	mA

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- All device terminals except FCT162XXX Output and I/O terminals.
- Outputs and I/O terminals for FCT162XXX.

CAPACITANCE (T_A = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	3.5	6	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	3.5	8	pF

NOTE:

- This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description
xDx	Data Inputs
xLE	Latch Enable Inputs (Active HIGH)
xOE	Output Enable Inputs (Active LOW)
xQx	3-State Outputs

FUNCTION TABLE⁽¹⁾

Inputs			Outputs
xDx	xLE	xOE	xQx
H	H	L	H
L	H	L	L
X	L	L	Q ⁽²⁾
X	X	H	Z

NOTES:

- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
Z = High-Impedance
- Output Level before xLE HIGH-to-LOW transition.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{CC} = 5.0\text{V} \pm 10\%$

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
V_{IH}	Input HIGH Level	Guaranteed Logic HIGH Level		2	—	—	V
V_{IL}	Input LOW Level	Guaranteed Logic LOW Level		—	—	0.8	V
I_{IH}	Input HIGH Current (Input pins) ⁽⁵⁾	$V_{CC} = \text{Max.}$	$V_I = V_{CC}$	—	—	± 1	μA
	Input HIGH Current (I/O pins) ⁽⁵⁾		$V_I = \text{GND}$	—	—	± 1	
I_{IL}	Input LOW Current (Input pins) ⁽⁵⁾		$V_I = \text{GND}$	—	—	± 1	
	Input LOW Current (I/O pins) ⁽⁵⁾		$V_I = \text{GND}$	—	—	± 1	
I_{OZH}	High Impedance Output Current (3-State Output pins) ⁽⁵⁾	$V_{CC} = \text{Max.}$	$V_O = 2.7\text{V}$	—	—	± 1	μA
I_{OZL}			$V_O = 0.5\text{V}$	—	—	± 1	
V_{IK}	Clamp Diode Voltage	$V_{CC} = \text{Min.}, I_{IN} = -18\text{mA}$		—	-0.7	-1.2	V
I_{OS}	Short Circuit Current	$V_{CC} = \text{Max.}, V_O = \text{GND}^{(3)}$		-80	-140	-250	mA
V_H	Input Hysteresis	—		—	100	—	mV
I_{CCL}	Quiescent Power Supply Current	$V_{CC} = \text{Max}$		—	5	500	μA
I_{CCH}		$V_{IN} = \text{GND or } V_{CC}$					
I_{CCZ}		$V_{IN} = \text{GND or } V_{CC}$					

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
I_O	Output Drive Current	$V_{CC} = \text{Max.}, V_O = 2.5\text{V}^{(3)}$		-50	—	-180	mA
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}$ $V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -3\text{mA}$	2.5	3.5	—	V
			$I_{OH} = -15\text{mA}$	2.4	3.5	—	V
			$I_{OH} = -32\text{mA}^{(4)}$	2	3	—	V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}$ $V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = 64\text{mA}$	—	0.2	0.55	V
I_{OFF}	Input/Output Power Off Leakage ⁽⁵⁾	$V_{CC} = 0\text{V}, V_{IN}$ or $V_O \leq 4.5\text{V}$		—	—	± 1	μA

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at $V_{CC} = 5.0\text{V}$, $+25^{\circ}\text{C}$ ambient.
3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
4. Duration of the condition can not exceed one second.
5. This test limit for this parameter is $\pm 5\mu\text{A}$ at $T_A = -55^{\circ}\text{C}$.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
ΔI_{CC}	Quiescent Power Supply Current TTL Inputs HIGH	V _{CC} = Max. V _{IN} = 3.4V ⁽³⁾		—	0.5	1.5	mA
I _{CCD}	Dynamic Power Supply Current ⁽⁴⁾	V _{CC} = Max. Outputs Open x \overline{OE} = GND One Input Toggling 50% Duty Cycle	V _{IN} = V _{CC} V _{IN} = GND	—	60	100	μ A/ MHz
I _C	Total Power Supply Current ⁽⁶⁾	V _{CC} = Max. Outputs Open f _i = 10MHz 50% Duty Cycle x \overline{OE} = GND xLE = V _{CC} One Bit Toggling	V _{IN} = V _{CC} V _{IN} = GND	—	0.6	1.5	mA
		V _{CC} = Max. Outputs Open f _i = 2.5MHz 50% Duty Cycle x \overline{OE} = GND xLE = V _{CC} Twenty Bits Toggling	V _{IN} = V _{CC} V _{IN} = GND	—	3	5.5 ⁽⁵⁾	
			V _{IN} = 3.4V V _{IN} = GND	—	0.9	2.3	
			V _{IN} = 3.4V V _{IN} = GND	—	8	20.5 ⁽⁵⁾	

NOTES:

- For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at V_{CC} = 5.0V, +25°C ambient.
- Per TTL driven input (V_{IN} = 3.4V). All other inputs at V_{CC} or GND.
- This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.
- I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}
 $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_{CP} N_{CP} / 2 + f_i N_i)$
 I_{CC} = Quiescent Current (I_{CC1}, I_{CCH} and I_{CCZ})
 ΔI_{CC} = Power Supply Current for a TTL High Input (V_{IN} = 3.4V)
 D_H = Duty Cycle for TTL Inputs High
 N_T = Number of TTL Inputs at D_H
 I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
 f_{CP} = Clock Frequency for Register Devices (Zero for Non-Register Devices)
 N_{CP} = Number of Clock Inputs at f_{CP}
 f_i = Input Frequency
 N_i = Number of Inputs at f_i

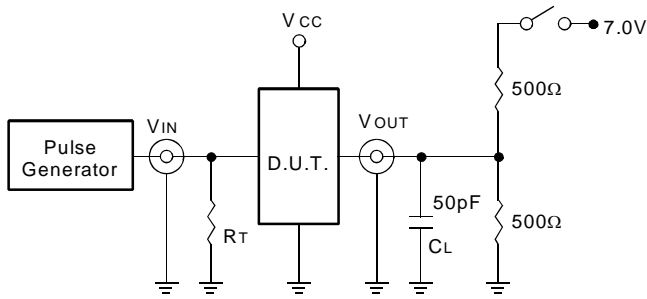
SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Symbol	Parameter	Condition ⁽¹⁾	74FCT16841AT		74FCT16841CT		Unit
			Min. ⁽²⁾	Max.	Min. ⁽²⁾	Max.	
t _{PLH} t _{PHL}	Propagation Delay xDx to xQx (LE = HIGH)	CL = 50pF RL = 500Ω	1.5	9	1.5	3.8	ns
		CL = 300pF ⁽³⁾ RL = 500Ω	1.5	13	1.5	7.5	
t _{PLH} t _{PHL}	Propagation Delay xLE to xQx	CL = 50pF RL = 500Ω	1.5	12	1.5	3.8	ns
		CL = 300pF ⁽³⁾ RL = 500Ω	1.5	16	1.5	7.5	
t _{PZH} t _{PZL}	Output Enable Time xOE to xQx	CL = 50pF RL = 500Ω	1.5	11.5	1.5	4.6	ns
		CL = 300pF ⁽³⁾ RL = 500Ω	1.5	23	1.5	9	
t _{PHZ} t _{PLZ}	Output Disable Time xOE to xQx	CL = 5pF ⁽³⁾ RL = 500Ω	1.5	7	1.5	3.6	ns
		CL = 50pF RL = 500Ω	1.5	8	1.5	3.6	
t _{SU}	Set-Up Time HIGH or LOW, xDx to xLE	CL = 50pF RL = 500Ω	2.5	—	1	—	ns
t _H	Hold Time HIGH or LOW, xDx to xLE		2.5	—	1	—	ns
t _W	xLE Pulse Width HIGH		4 ⁽⁵⁾	—	3 ⁽⁵⁾	—	ns
t _{SK(o)}	Output Skew ⁽⁴⁾		—	0.5	—	0.5	ns

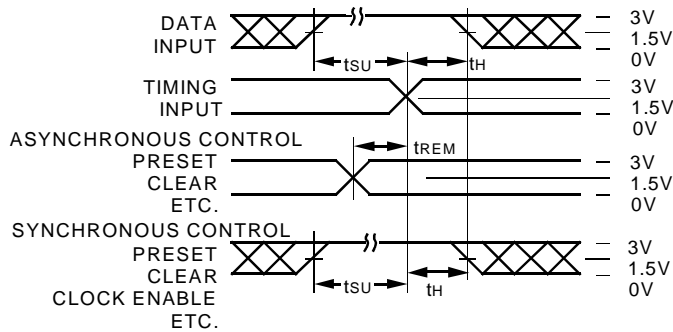
NOTES:

1. See test circuit and waveforms.
2. Minimum limits are guaranteed but not tested on Propagation Delays.
3. This condition is guaranteed but not tested.
4. Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.
5. This limit is guaranteed but not tested.

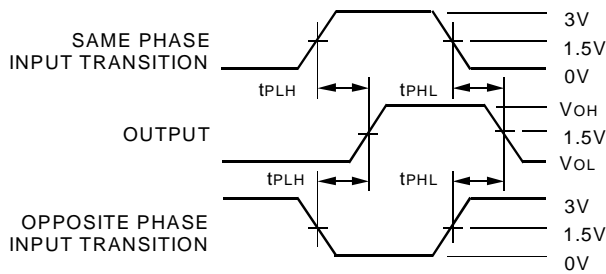
TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs



Set-up, Hold, and Release Times



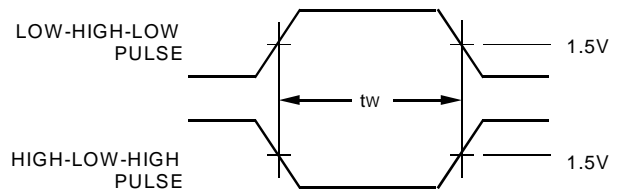
Propagation Delay

SWITCH POSITION

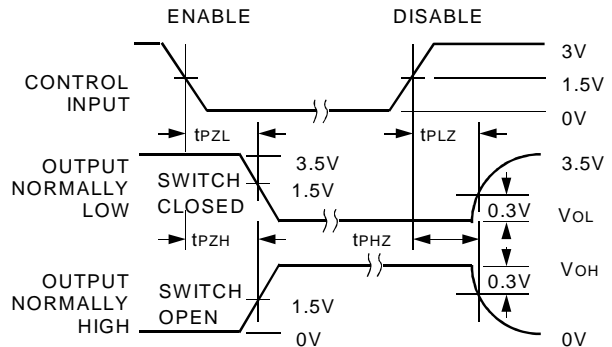
Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.
RT = Termination resistance: should be equal to ZOUT of the Pulse Generator.



Pulse Width

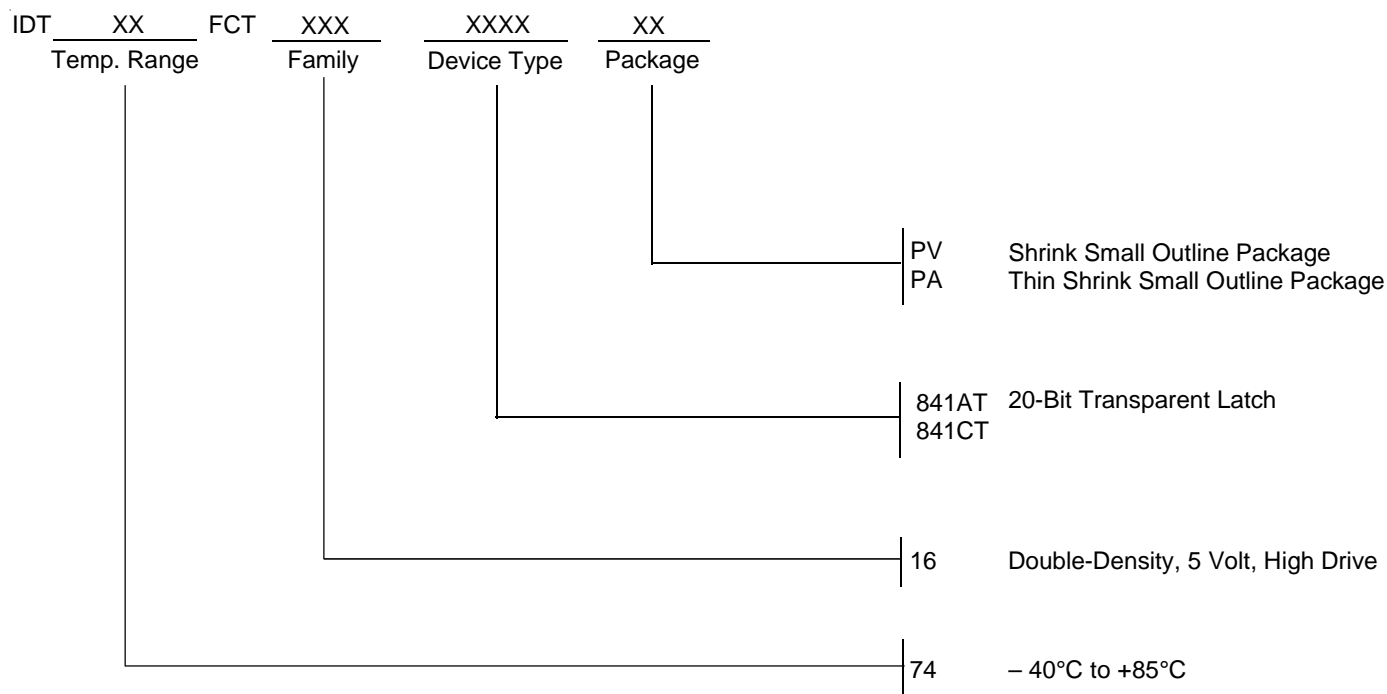


Enable and Disable Times

NOTES:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
2. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; tr ≤ 2.5ns; tr ≤ 2.5ns.

ORDERING INFORMATION



DATA SHEET DOCUMENT HISTORY

6/24/2002 Updated as per PDNs Logic-00-07 and Logic-01-04



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